

Amendments to the Specification

Please amend the following new paragraph on page 1, paragraph [0001] as follows.

[0001] The present application is a National Stage of International Application No. PCT/US03.10725, filed April 8, 2003, which claims priority of earlier filed provisional applications U.S. Application Nos. 60/372,542, entitled "MAINFRAMES FOR ELECTROPOLISHING AND/OR ELECTROPLATING AND/OR ELECTROPLATING ASSEMBLY," filed on April 14, 2002; No. 60/379,919 60/370,919, entitled "END EFFECTOR SEAL," filed on April 8, 2002; No. 60/370,955, entitled "METHOD AND APPARATUS FOR WAFER CLEANING," filed on April 8, 2002; No. 60/372,566, entitled "METHOD AND APPARATUS FOR ELECTROPOLISHING AND/OR ELECTROPLATING," filed on April 14, 2002; No. 60/370,956, entitled "METHOD AND APPARATUS FOR DELIVERING LIQUID," filed on April 8, 2002; No. 60/370,929 , entitled "METHOD AND APPARATUS FOR LEVELING WAFER," filed on April 8, 2002; No. 60/372,567, entitled "METHOD AND APPARATUS FOR ELECTROPOLISHING METAL FILM ON SUBSTRATE," filed on April 14, 2002; and No. 60/390,460, entitled "ELECTROPLATING APPARATUS," filed on June 21, 2002, all of which are incorporated herein by reference in their entirety.